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## \*BIBDATASHEET\*

Bib Data Sheet

CONFIRMATION NO. 3830

SERIAL NUMBER. 09/991,166	FILING DATE 11/16/2001 RULE	CLASS 438	GROUP ART UNIT 1765	ATTORNEY DOCKET NO. 05630 USA P 01/ETCH/METAL
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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

Verifd LV

This application is a CIP of 09/918,671 07/27/2001 PAT 6,770,567

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

Verf LV

REPUBLIC OF KOREA 10-2001-40309 07/06/2001

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 12/03/2001

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	CA	6	60	7
Verified and Acknowledged	Examiner's Signature <i>Verifd LV</i>	Initials			

## ADDRESS

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## TITLE

Method of reducing particulates in a plasma etch chamber during a metal etch process

 All Fees 1.16 Fees ( Filing )

FILING FEE FEES: Authority has been given in Paper